

Electronic Patent Application Fee Transmittal

Application Number:	10568755			
Filing Date:	21-Feb-2006			
Title of Invention:	Microsystem component and method for gluing microcomponents to a substrate			
First Named Inventor/Applicant Name:	Stefan Boehm			
Filer:	Michael E. Whitham/Linda Handler			
Attorney Docket Number:	03100282AA			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Claims in excess of 20	1615	1	52	52
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
Total in USD (\$)				1162